

# TC74HC251AP, TC74HC251AF

## 8 - CHANNEL MULTIPLEXER (3 - STATE)

The TC74HC251A is a high speed CMOS 8 - CHANNEL MULTIPLEXER fabricated with silicon gate C<sup>2</sup>MOS technology.

It achieves the high speed operation similar to equivalent LSTTL while maintaining the CMOS low power dissipation. One of eight data input signals (D0 - D7) is selected by decoding of the address input (A, B, C). The selected data appears on two outputs; non - inverting (Y) and inverting (W). When the strobe input is held high, both outputs are in the high-impedance state.

All inputs are equipped with protection circuits against static discharge or transient excess voltage.

### FEATURES :

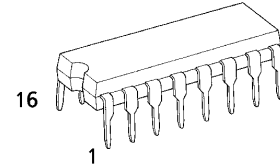
- High Speed..... $t_{pd} = 15\text{ns}(\text{typ.})$  at  $V_{CC} = 5\text{V}$
- Low Power Dissipation..... $I_{CC} = 4\mu\text{A}(\text{Max.})$  at  $T_a = 25^\circ\text{C}$
- High Noise Immunity..... $V_{NIH} = V_{NIL} = 28\% V_{CC} (\text{Min.})$
- Output Drive Capability..... 10 LSTTL Loads
- Symmetrical Output Impedance.....  $|I_{OH}| = I_{OL} = 4\text{mA}(\text{Min.})$
- Balanced Propagation Delays.....  $t_{pLH} \approx t_{pHL}$
- Wide Operating Voltage Range.....  $V_{CC} (\text{opr.}) = 2\text{V} \sim 6\text{V}$
- Pin and Function Compatible with 74LS251

### TRUTH TABLE

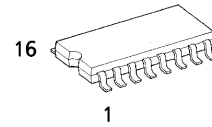
INPUTS				OUTPUTS	
SELECT			STROBE	Y	W
C	B	A	$\overline{ST}$		
X	X	X	H	Z	Z
L	L	L	L	D0	$\overline{D0}$
L	L	H	L	D1	$\overline{D1}$
L	H	L	L	D2	$\overline{D2}$
L	H	H	L	D3	$\overline{D3}$
H	L	L	L	D4	$\overline{D4}$
H	L	H	L	D5	$\overline{D5}$
H	H	L	L	D6	$\overline{D6}$
H	H	H	L	D7	$\overline{D7}$

X : Don't Care

H : High Impedance

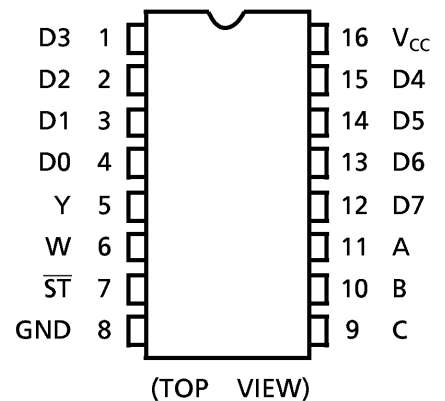


P (DIP16-P-300-2.54A)  
Weight : 1.00g (Typ.)

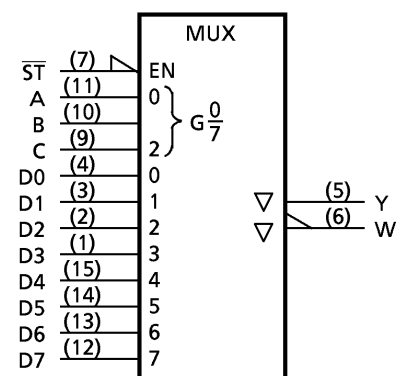


F (SOP16-P-300-1.27)  
Weight : 0.18g (Typ.)

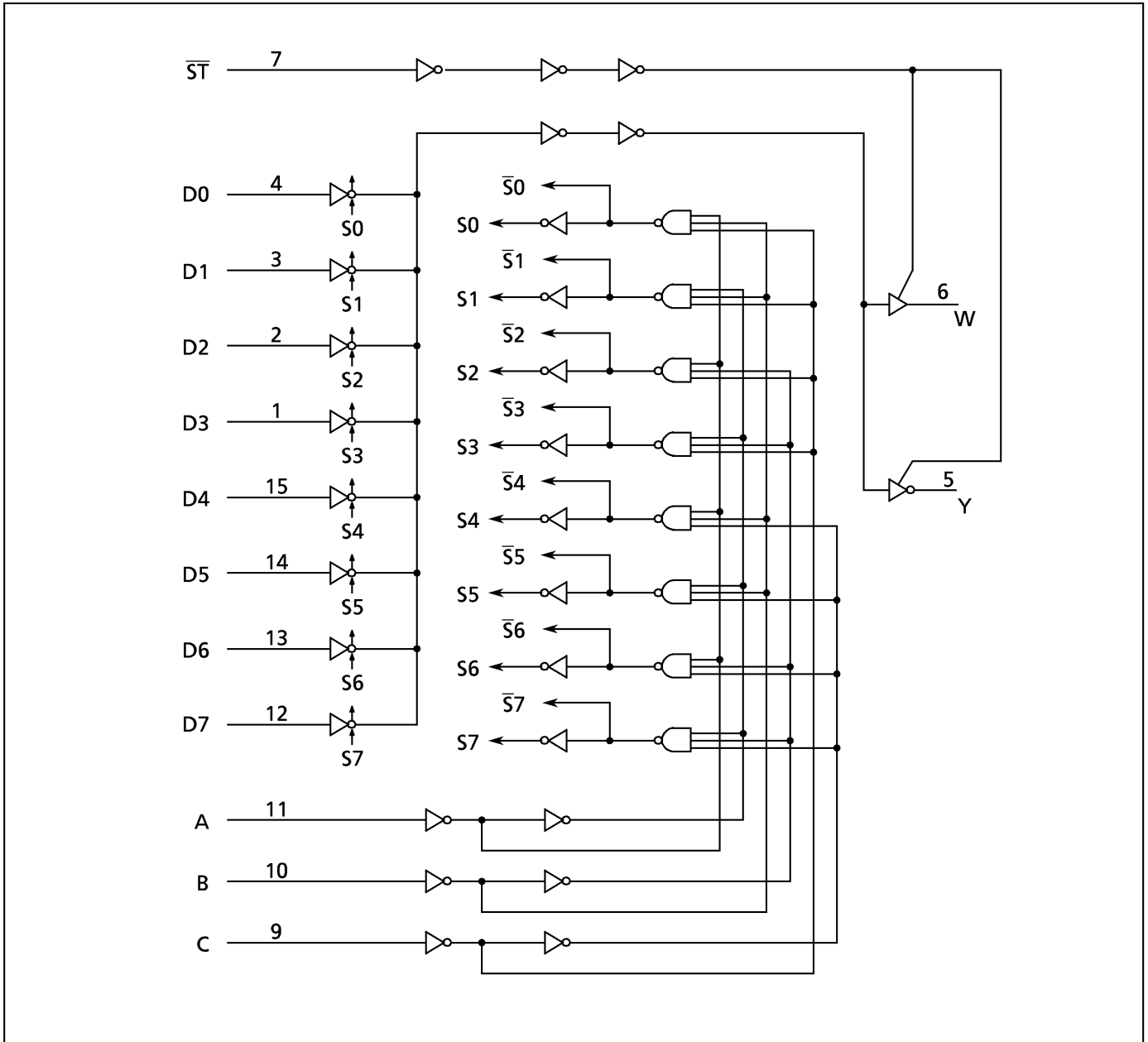
### PIN ASSIGNMENT



### IEC LOGIC SYMBOL



SYSTEM DIAGRAM



**ABSOLUTE MAXIMUM RATINGS**

PARAMETER	SYMBOL	VALUE	UNIT
Supply Voltage Range	$V_{CC}$	-0.5~7	V
DC Input Voltage	$V_{IN}$	-0.5~ $V_{CC}+0.5$	V
DC Output Voltage	$V_{OUT}$	-0.5~ $V_{CC}+0.5$	V
Input Diode Current	$I_{IK}$	$\pm 20$	mA
Output Diode Current	$I_{OK}$	$\pm 20$	mA
DC Output Current	$I_{OUT}$	$\pm 25$	mA
DC $V_{CC}$ / Ground Current	$I_{CC}$	$\pm 50$	mA
Power Dissipation	$P_D$	500 (DIP)* / 180 (SOP)	mW
Storage Temperature	$T_{stg}$	-65~150	°C

\*500mW in the range of  $T_a = -40^{\circ}\text{C} \sim 65^{\circ}\text{C}$ . From  $T_a = 65^{\circ}\text{C}$  to  $85^{\circ}\text{C}$  a derating factor of  $-10\text{mW}/^{\circ}\text{C}$  shall be applied until 300mW.

**RECOMMENDED OPERATING CONDITIONS**

PARAMETER	SYMBOL	VALUE	UNIT
Supply Voltage	$V_{CC}$	2~6	V
Input Voltage	$V_{IN}$	0~ $V_{CC}$	V
Output Voltage	$V_{OUT}$	0~ $V_{CC}$	V
Operating Temperature	$T_{opr}$	-40~85	°C
Input Rise and Fall Time	$t_r, t_f$	0~1000 ( $V_{CC} = 2.0\text{V}$ ) 0~500 ( $V_{CC} = 4.5\text{V}$ ) 0~400 ( $V_{CC} = 6.0\text{V}$ )	ns

**DC ELECTRICAL CHARACTERISTICS**

PARAMETER	SYMBOL	TEST CONDITION	$V_{CC}$ (V)	$T_a = 25^{\circ}\text{C}$			$T_a = -40 \sim 85^{\circ}\text{C}$		UNIT									
				MIN.	TYP.	MAX.	MIN.	MAX.										
High - Level Input Voltage	$V_{IH}$		2.0	1.50	—	—	1.50	—	V									
			4.5	3.15	—	—	3.15	—										
			6.0	4.20	—	—	4.20	—										
Low - Level Input Voltage	$V_{IL}$		2.0	—	—	0.50	—	0.50	V									
			4.5	—	—	1.35	—	1.35										
			6.0	—	—	1.80	—	1.80										
High - Level Output Voltage	$V_{OH}$	$V_{IN} = V_{IH}$ or $V_{IL}$	$I_{OH} = -20\mu\text{A}$	2.0	1.9	2.0	—	1.9	—	V								
				4.5	4.4	4.5	—	4.4	—									
				6.0	5.9	6.0	—	5.9	—									
Low - Level Output Voltage	$V_{OL}$	$V_{IN} = V_{IH}$ or $V_{IL}$	$I_{OL} = 20\mu\text{A}$	2.0	—	0.0	0.1	—	0.1	V								
				4.5	—	0.0	0.1	—	0.1									
				6.0	—	0.0	0.1	—	0.1									
3 - State Off Leak Current	$I_{OZ}$	$V_{IN} = V_{IH}$ or $V_{IL}$ $V_{OUT} = V_{CC}$ or GND	6.0	—	—	$\pm 0.5$	—	$\pm 5.0$	$\mu\text{A}$									
										Input Leakage Current	$I_{IN}$	$V_{IN} = V_{CC}$ or GND	6.0	—	—	$\pm 0.1$	—	$\pm 1.0$

**AC ELECTRICAL CHARACTERISTICS (C<sub>L</sub> = 15pF, V<sub>CC</sub> = 5V, Ta = 25°C, Input t<sub>r</sub> = t<sub>f</sub> = 6ns)**

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Output Transition Time	t <sub>TLH</sub> t <sub>THL</sub>		—	4	8	ns
Propagation Delay Time (D–Y)	t <sub>pLH</sub> t <sub>pHL</sub>		—	14	24	
Propagation Delay Time (D–W)	t <sub>pLH</sub> t <sub>pHL</sub>		—	15	24	
Propagation Delay Time (A, B, C–Y)	t <sub>pLH</sub> t <sub>pHL</sub>		—	19	31	
Propagation Delay Time (A, B, C–W)	t <sub>pLH</sub> t <sub>pHL</sub>		—	19	31	
3-State Output Enable Time	t <sub>pZL</sub> t <sub>pZH</sub>		—	10	18	

**AC ELECTRICAL CHARACTERISTICS (C<sub>L</sub> = 50pF, Input t<sub>r</sub> = t<sub>f</sub> = 6ns)**

PARAMETER	SYMBOL	TEST CONDITION	Ta = 25°C			Ta = –40–85°C		UNIT
			V <sub>CC</sub> (V)	MIN.	TYP.	MAX.	MIN.	
Output Transition Time	t <sub>TLH</sub> t <sub>THL</sub>		2.0	—	30	75	—	95
			4.5	—	8	15	—	19
			6.0	—	7	13	—	16
Propagation Delay Time (D–Y)	t <sub>pLH</sub> t <sub>pHL</sub>		2.0	—	65	140	—	175
			4.5	—	17	28	—	35
			6.0	—	14	24	—	30
Propagation Delay Time (D–W)	t <sub>pLH</sub> t <sub>pHL</sub>		2.0	—	70	140	—	175
			4.5	—	18	28	—	35
			6.0	—	15	24	—	30
Propagation Delay Time (A, B, C–Y)	t <sub>pLH</sub> t <sub>pHL</sub>		2.0	—	80	180	—	225
			4.5	—	23	36	—	45
			6.0	—	19	31	—	38
Propagation Delay Time (A, B, C–W)	t <sub>pLH</sub> t <sub>pHL</sub>		2.0	—	80	180	—	225
			4.5	—	23	36	—	45
			6.0	—	19	31	—	38
3-State Output Enable Time	t <sub>pZL</sub> t <sub>pZH</sub>		2.0	—	40	105	—	130
			4.5	—	13	21	—	26
			6.0	—	10	19	—	22
3-State Output Disable Time	t <sub>pLZ</sub> t <sub>pHZ</sub>		2.0	—	25	105	—	130
			4.5	—	13	21	—	26
			6.0	—	11	19	—	22
Input Capacitance	C <sub>IN</sub>		—	5	10	—	10	pF
Power Dissipation Capacitance	C <sub>PD</sub> (1)		—	69	—	—	—	

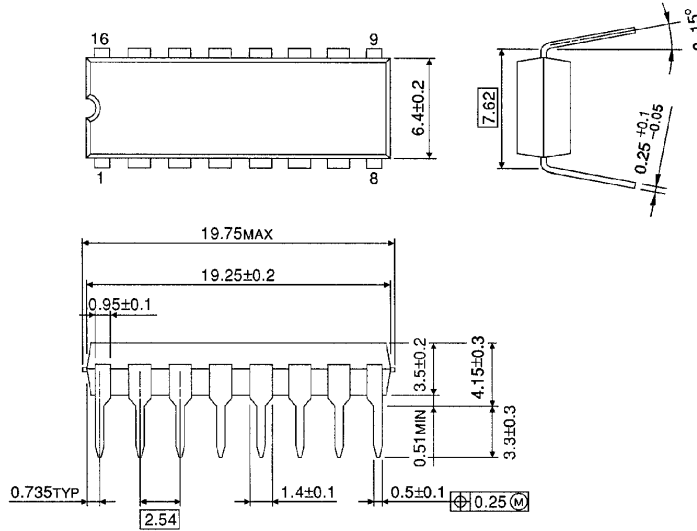
Note (1) C<sub>PD</sub> is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load.

Average operating current can be obtained by the equation :

$$I_{CC}(\text{opr}) = C_{PD} \cdot V_{CC} \cdot f_{IN} + I_{CC}$$

**DIP 16PIN PACKAGE DIMENSIONS (DIP16-P-300-2.54A)**

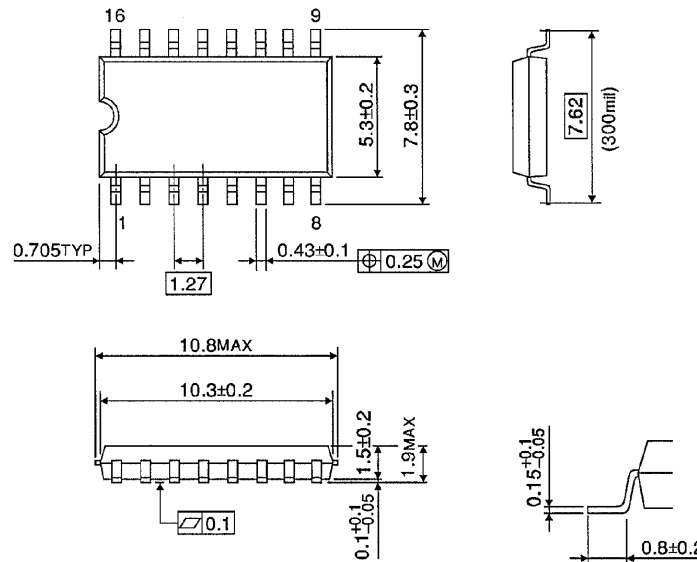
Unit in mm



Weight : 1.00g (Typ.)

**SOP 16PIN (200mil BODY) PACKAGE DIMENSIONS (SOP16-P-300-1.27)**

Unit in mm



Weight : 0.18g (Typ.)

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000707EBA

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